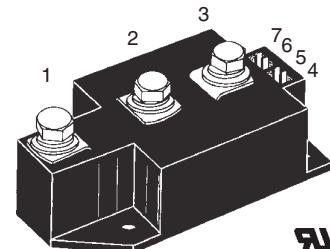


Thyristor Modules

Thyristor/Diode Modules

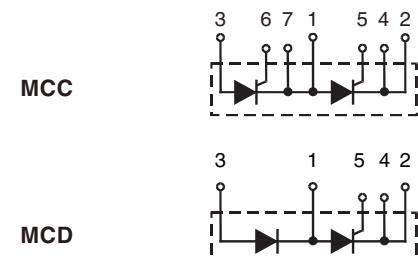
I_{TRMS} = 2x450 A
I_{TAVM} = 2x287 A
V_{RRM} = 800-1800 V

V _{RSM} V _{DSM}	V _{RRM} V _{DRM}	Type	
V	V	Version 1	Version 1
900	800	MCC 250-08io1	MCD 250-08io1
1300	1200	MCC 250-12io1	MCD 250-12io1
1500	1400	MCC 250-14io1	MCD 250-14io1
1700	1600	MCC 250-16io1	MCD 250-16io1
1900	1800	MCC 250-18io1	MCD 250-18io1



Symbol	Conditions	Maximum Ratings		
I _{TRMS} , I _{FRMS}	T _{VJ} = T _{VJM}	450	A	
I _{TAVM} , I _{FAVM}	T _C = 85°C; 180° sine	287	A	
I _{TSM} , I _{FSM}	T _{VJ} = 45°C	t = 10 ms (50 Hz), sine	9000	A
	V _R = 0	t = 8.3 ms (60 Hz), sine	9600	A
	T _{VJ} = T _{VJM}	t = 10 ms (50 Hz), sine	7800	A
	V _R = 0	t = 8.3 ms (60 Hz), sine	8500	A
$\int i^2 dt$	T _{VJ} = 45°C	t = 10 ms (50 Hz), sine	405 000	A ² s
	V _R = 0	t = 8.3 ms (60 Hz), sine	380 000	A ² s
	T _{VJ} = T _{VJM}	t = 10 ms (50 Hz), sine	304 000	A ² s
	V _R = 0	t = 8.3 ms (60 Hz), sine	300 000	A ² s
(di/dt) _{cr}	T _{VJ} = T _{VJM} ; f = 50 Hz; t _p = 200 µs V _D = $\frac{2}{3} V_{DRM}$	repetitive, I _T = 860 A	100	A/µs
	I _G = 1 A; di _G /dt = 1 A/µs	non repetitive, I _T = 290 A	800	A/µs
(dv/dt) _{cr}	T _{VJ} = T _{VJM} ; R _{GK} = ∞; method 1 (linear voltage rise)	V _{DR} = $\frac{2}{3} V_{DRM}$	1000	V/µs
P _{GM}	T _{VJ} = T _{VJM} ; I _T = I _{TAVM} ;	t _p = 30 µs t _p = 500 µs	120 60	W W
P _{GAV}			20	W
V _{RGM}			10	V
T _{VJ}			-40...+140	°C
T _{VJM}			140	°C
T _{stg}			-40...+125	°C
V _{ISOL}	50/60 Hz, RMS; I _{ISOL} ≤ 1 mA;	t = 1 min t = 1 s	3000 3600	V~ V~
M _d	Mounting torque (M5) Terminal connection torque (M8)		2.5-5/22-44 Nm/lb.in. 12-15/106-132 Nm/lb.in.	
Weight	Typical including screws		320	g

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.
 IXYS reserves the right to change limits, test conditions and dimensions



Features

- International standard package
- Direct copper bonded Al₂O₃-ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873
- Keyed gate/cathode twin pins

Applications

- Motor control
- Power converter
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Contactless switches

Advantages

- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

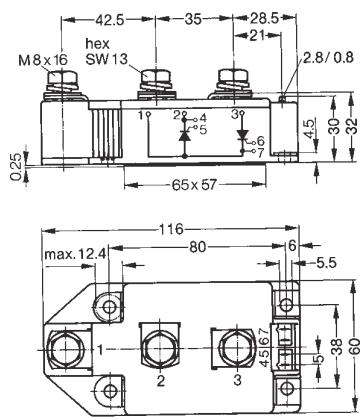
Symbol	Conditions	Characteristic Values	
I_{RRM}	$T_{VJ} = T_{VJM}$; $V_R = V_{RRM}$; $V_D = V_{DRM}$	70	mA
I_{DRM}		40	mA
V_T, V_F	$I_T/I_F = 600 A$; $T_{VJ} = 25^\circ C$	1.36	V
V_{TO}	For power-loss calculations only ($T_{VJ} = 140^\circ C$)	0.85	V
r_T		0.82	$\text{m}\Omega$
V_{GT}	$V_D = 6 V$; $T_{VJ} = 25^\circ C$	2	V
	$T_{VJ} = -40^\circ C$	3	V
I_{GT}	$V_D = 6 V$; $T_{VJ} = 25^\circ C$	150	mA
	$T_{VJ} = -40^\circ C$	200	mA
V_{GD}	$T_{VJ} = T_{VJM}$; $V_D = \frac{2}{3} V_{DRM}$	0.25	V
I_{GD}		10	mA
I_L	$T_{VJ} = 25^\circ C$; $t_p = 30 \mu s$; $V_D = 6 V$ $I_G = 0.45 A$; $di_G/dt = 0.45 A/\mu s$	200	mA
I_H	$T_{VJ} = 25^\circ C$; $V_D = 6 V$; $R_{GK} = \infty$	150	mA
t_{gd}	$T_{VJ} = 25^\circ C$; $V_D = \frac{1}{2} V_{DRM}$ $I_G = 1 A$; $di_G/dt = 1 A/\mu s$	2	μs
t_q	$T_{VJ} = T_{VJM}$; $I_T = 300 A$, $t_p = 200 \mu s$; $-di/dt = 10 A/\mu s$ $V_R = 100 V$; $dv/dt = 50 V/\mu s$; $V_D = \frac{2}{3} V_{DRM}$	typ. 200	μs
Q_s	$T_{VJ} = 125^\circ C$; $I_T/I_F = 400 A$, $-di/dt = 50 A/\mu s$	760	μC
I_{RM}		275	A
R_{thJC}	per thyristor/diode; DC current	0.129	K/W
	per module	0.0645	K/W
R_{thJK}	per thyristor/diode; DC current	0.169	K/W
	per module	0.0845	K/W
d_s	Creepage distance on surface	12.7	mm
d_A	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

Optional accessories for modules

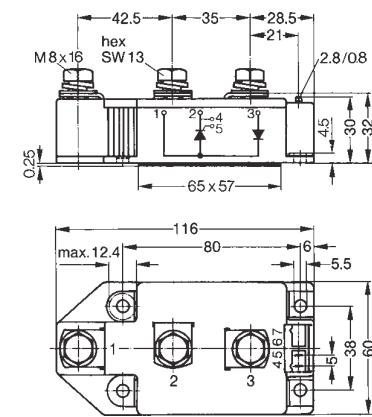
Keyed gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red
Type **ZY 180L** (L = Left for pin pair 4/5) } UL 758, style 1385,
Type **ZY 180R** (R = right for pin pair 6/7) } CSA class 5851, guide 460-1-1

Dimensions in mm (1 mm = 0.0394")

MCC



MCD



IXYS reserves the right to change limits, test conditions and dimensions

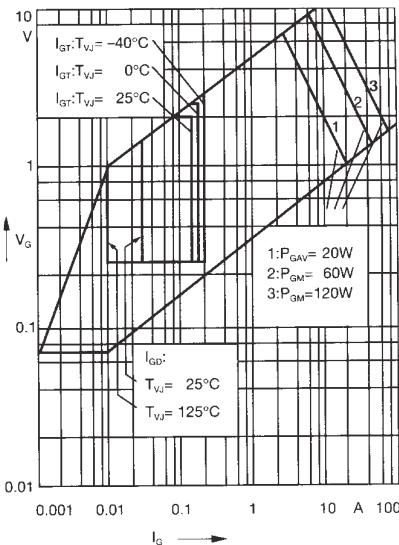


Fig. 1 Gate trigger characteristics

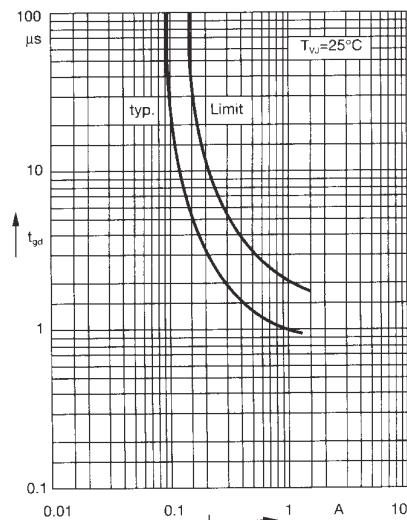
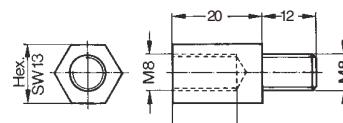


Fig. 2 Gate trigger delay time

Threaded spacer for higher Anode/Cathode construction:
Type **ZY 250**, material brass



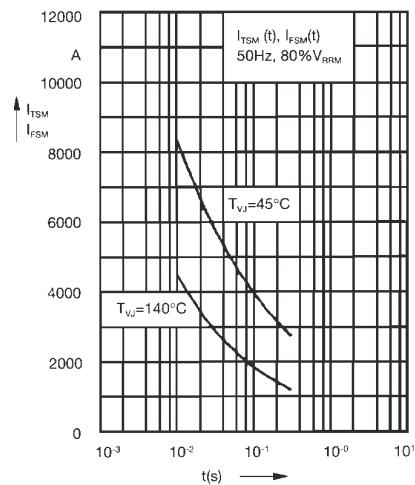


Fig. 3 Surge overload current
 I_{TSM}, I_{FSM} : Crest value, t : duration

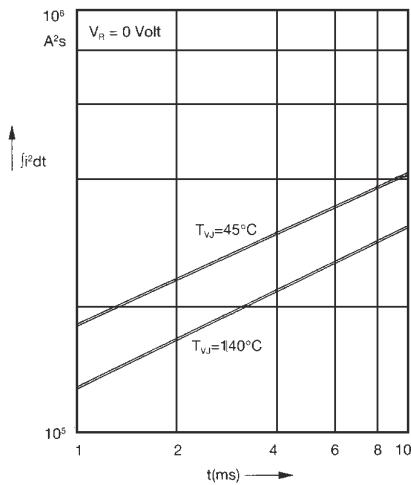


Fig. 4 $\int i^2 dt$ versus time (1-10 ms)

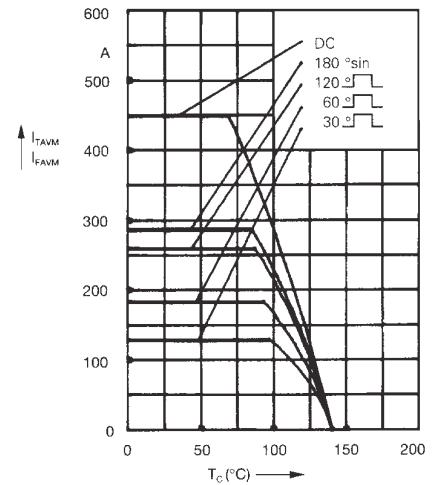


Fig. 4a Maximum forward current at case temperature

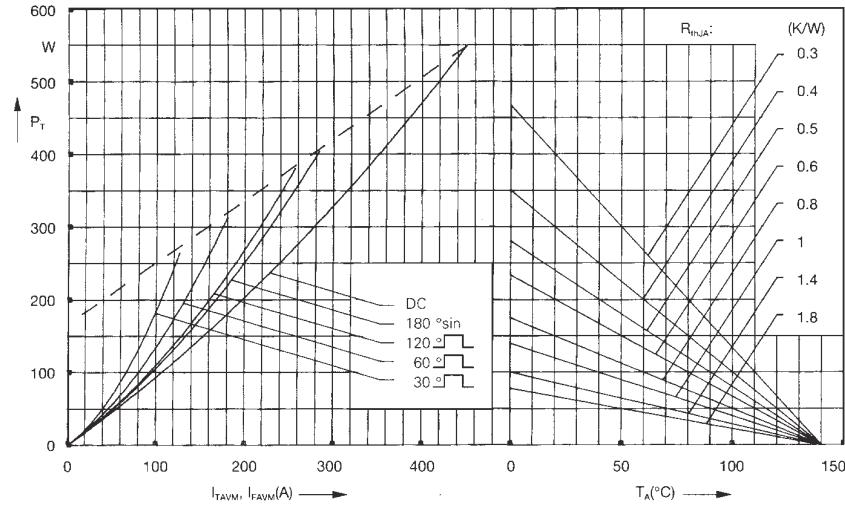


Fig. 5 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

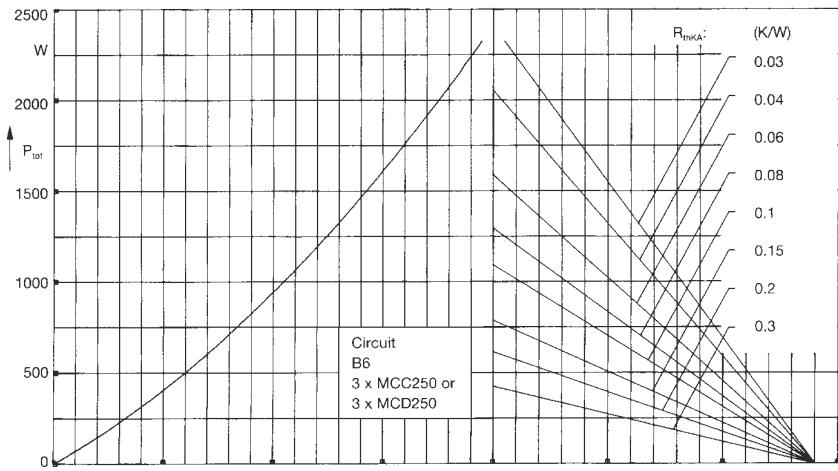
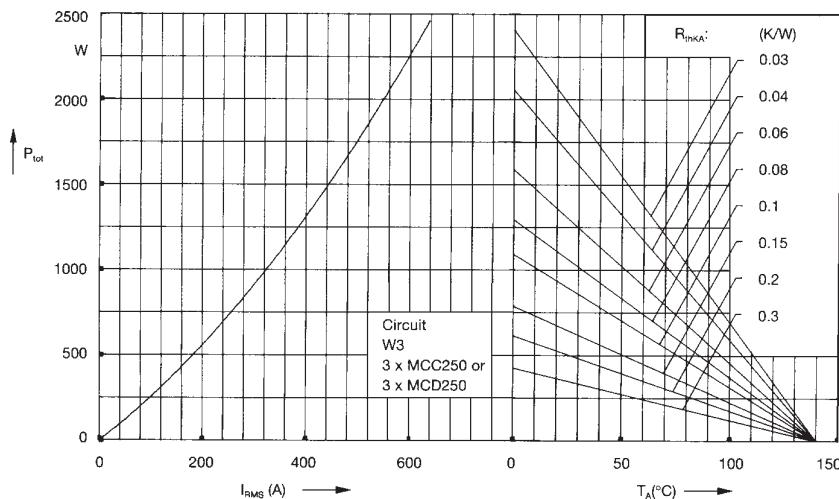
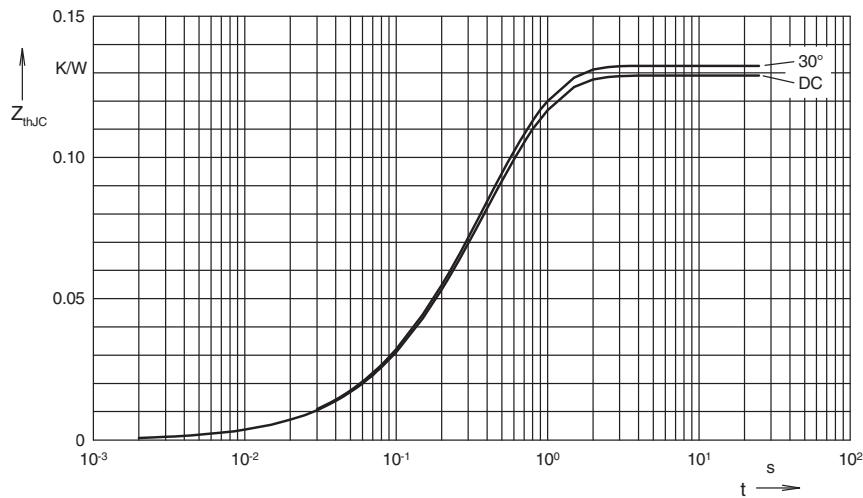


Fig. 6 Three phase rectifier bridge:
Power dissipation versus direct output current and ambient temperature



**Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature**



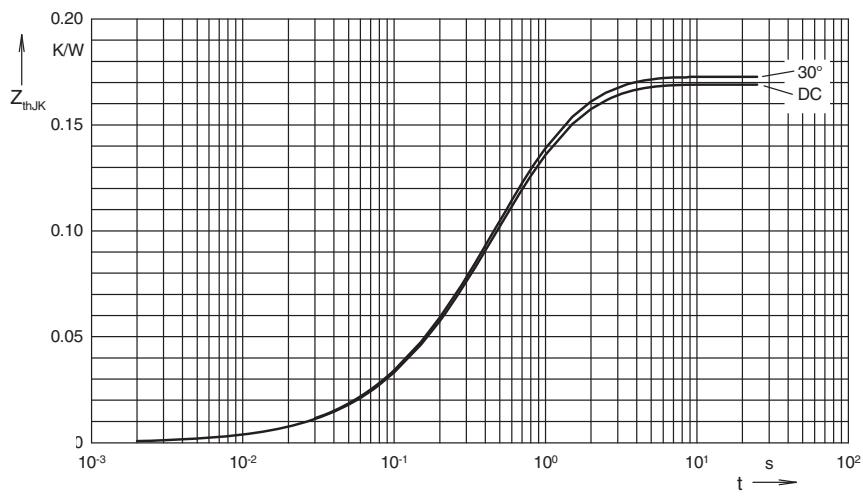
**Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)**

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.129
180°C	0.131
120°C	0.131
60°C	0.132
30°C	0.132

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.099
2	0.0165	0.168
3	0.1091	0.456



**Fig. 9 Transient thermal impedance
junction to heatsink (perthyristor
or diode)**

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.169
180°C	0.171
120°C	0.172
60°C	0.172
30°C	0.173

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0033	0.099
2	0.0159	0.168
3	0.1053	0.456
4	0.04	1.36